

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		AMS/18/10965
1.3 Title of PCN		Qualification of TSHT (Subcon) as additional Assy & TnF plant for several SO8 packages.
1.4 Product Category		See Products List.
1.5 Issue date		2018-06-19

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO
2.2.2 Marketing Manager	Fulvio PULICELLI
2.2.3 Quality Manager	Alessandro PLATINI

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Shenzhen and TSHT (Subcon) as Assy and TnF plants.

### 4. Description of change

	Old	New
4.1 Description	Shenzhen as Assy and TnF plant.	TSHT (Subcon) as Assy and TnF plant in second-source.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Negligible Impact	

### 5. Reason / motivation for change

5.1 Motivation	The qualification of TSHT (Subcon) as additional plant for Assy and Test & Finishing activities is done to further improve the rationalization of our manufacturing assets, to provide a better support to our customers by enhancing the manufacturing process for higher volume production.
5.2 Customer Benefit	CAPACITY INCREASE

### 6. Marking of parts / traceability of change

6.1 Description	New dedicated Finish Goods.
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### 7. Timing / schedule

7.1 Date of qualification results	2018-08-31
7.2 Intended start of delivery	2018-09-30
7.3 Qualification sample available?	Upon Request

### 8. Qualification / Validation

8.1 Description	10965 10892 ExternalReliabilityEvaluationReport_0158_0922_0082_TSHT-LP.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-06-19

**9. Attachments (additional documentations)**

10965 Public product.pdf  
10965 10892 ExternalReliabilityEvaluationReport\_0158\_0922\_0082\_TSHT-LP.pdf

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
TSM103WAID	TSM103WAID	
TSM103WAIDT	TSM103WAIDT	
TSM103WIDT	TSM103WIDT	
VIPER12AS-E	VIPER12AS-E	
VIPER12ASTR-E	VIPER12ASTR-E	
VIPER22AS-E	VIPER22AS-E	
	VIPER22ASTR-E	

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